

Taiwan Semiconductor

# 5000W, 16V - 100V Surface Mount Transient Voltage Suppressor

## FEATURES

- 5000W peak pulse power capability at 10/1000µs waveform
- Ideal for automated placement
- Photo glass passivated chip junction
- Excellent clamping capability
- Fast response time: Typically less than 1.0ps
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

## APPLICATIONS

- I/O interface
- AC/DC power supply

### **MECHANICAL DATA**

- Case: DO-214AB (SMC)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.300g (approximately)

KEY PARAMETERS				
PARAMETER	VALUE	UNIT		
V <sub>WM</sub>	16 - 100	V		
V <sub>BR</sub> (uni-directional)	17.8 - 123	V		
P <sub>PPSM</sub>	5000	W		
T <sub>J MAX</sub>	175	°C		
Package	DO-214AB (SMC)			
Configuration	Stacked die			





DO-214AB (SMC)



ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER	SYMBOL	VALUE	UNIT		
Non-repetitive peak impulse power dissipation with 10/1000us waveform <sup>(1)</sup>	P <sub>PK</sub>	5000	W		
Steady state power dissipation at $T_L = 75^{\circ}C^{(2)}$	P <sub>D</sub>	6.25	W		
Forward Voltage @ $I_F = 100A$ for Uni-directional only <sup>(3)</sup>	V <sub>F</sub>	5	V		
Junction temperature	TJ	-55 to +175	°C		
Storage temperature	T <sub>STG</sub>	-55 to +175	°C		

#### Notes:

1. Non-repetitive current pulse per Fig.3 and derated above  $T_A = 25^{\circ}C$  per Fig.1

- 2. Units mounted on PCB (16mm x 16mm Cu pad test board)
- 3. Pulse test with PW = 0.3ms

THERMAL PERFORMANCE					
PARAMETER	SYMBOL	ТҮР	UNIT		
Junction-to-lead thermal resistance	$R_{\Theta JL}$	16	°C/W		
Junction-to-ambient thermal resistance	R <sub>eja</sub>	61	°C/W		
Junction-to-case thermal resistance	R <sub>eJC</sub>	17	°C/W		

Thermal Performance Note: Units mounted on PCB (16mm x 16mm Cu pad test board)



Part number	Marking code	Breako volta V <sub>BR</sub> @ (V (Note	age ⊇I <sub>T</sub> )	Test current I <sub>T</sub> (mA)	Working stand- off voltage V <sub>WM</sub>	leakage current I <sub>IB</sub> @V <sub>WM</sub>	Maximum peak impulse current I <sub>PP</sub>	Maximum clamping voltage V <sub>C</sub> @I <sub>PP</sub> (V)	Maximum Temp. coefficient of V <sub>BR</sub> αV <sub>BR</sub> @I <sub>T</sub>
Uni	Uni	Min	Max		(V)	(µA) (Note 1)	(A)	(v)	(mV/°C)
5.0SMDJ16A	5PET	17.8	19.7	1	16	50	193	26.0	0.096
5.0SMDJ17A	5PEU	18.9	20.9	1	17	20	181	27.6	0.097
5.0SMDJ18A	5PEV	20.0	22.1	1	18	10	172	29.2	0.098
5.0SMDJ20A	5PEW	22.2	24.5	1	20	5	155	32.4	0.099
5.0SMDJ22A	5PEX	24.4	26.9	1	22	5	141	35.5	0.100
5.0SMDJ24A	5PEZ	26.7	29.5	1	24	2	129	38.9	0.101
5.0SMDJ26A	5PFE	28.9	31.9	1	26	2	119	42.1	0.101
5.0SMDJ28A	5PFG	31.1	34.4	1	28	2	110	45.4	0.102
5.0SMDJ30A	5PFK	33.3	36.8	1	30	2	103	48.4	0.103
5.0SMDJ33A	5PFM	36.7	40.6	1	33	2	93.9	53.3	0.104
5.0SMDJ36A	5PFP	40.0	44.2	1	36	2	86.1	58.1	0.104
5.0SMDJ40A	5PFR	44.4	49.1	1	40	2	77.6	64.5	0.105
5.0SMDJ43A	5PFT	47.8	52.8	1	43	2	72.1	69.4	0.105
5.0SMDJ45A	5PFV	50.0	55.3	1	45	2	68.8	72.7	0.106
5.0SMDJ48A	5PFX	53.3	58.9	1	48	2	64.7	77.4	0.106
5.0SMDJ51A	5PFZ	56.7	62.7	1	51	2	60.7	82.4	0.107
5.0SMDJ54A	5PGE	60.0	66.3	1	54	2	57.5	87.1	0.107
5.0SMDJ58A	5PGG	64.4	71.2	1	58	2	53.5	93.6	0.107
5.0SMDJ60A	5PGK	66.7	73.7	1	60	2	51.7	96.8	0.108
5.0SMDJ64A	5PGM	71.1	78.6	1	64	2	48.6	103	0.108
5.0SMDJ70A	5PGP	77.8	86.0	1	70	2	44.3	113	0.108
5.0SMDJ75A	5PGR	83.3	92.1	1	75	2	41.4	121	0.108
5.0SMDJ78A	5PGT	86.7	95.8	1	78	2	39.7	126	0.108
5.0SMDJ85A	5PGV	94.4	104	1	85	2	36.5	137	0.110
5.0SMDJ90A	5PGX	100	111	1	90	2	34.3	146	0.110
5.0SMDJ100A	5PGZ	111	123	1	100	2	30.9	162	0.110

Note:

1. Pulse test with PW = 30ms

ORDERING INFORMATION					
ORDERING CODE <sup>(1)</sup> PACKAGE PACKING					
5.0SMDJx	DO-214AB (SMC)	3,000 / Tape & Reel			

Notes:

1. "x" defines voltage from 16V(5.0SMDJ16A) to 100V(5.0SMDJ100A)



Taiwan Semiconductor

### **CHARACTERISTICS CURVES**

(T<sub>A</sub> = 25°C unless otherwise noted)

#### Fig.1 Pulse Power or Current vs. Initial Junction

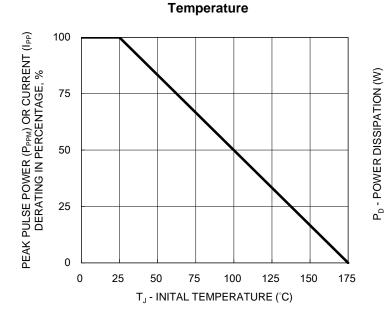
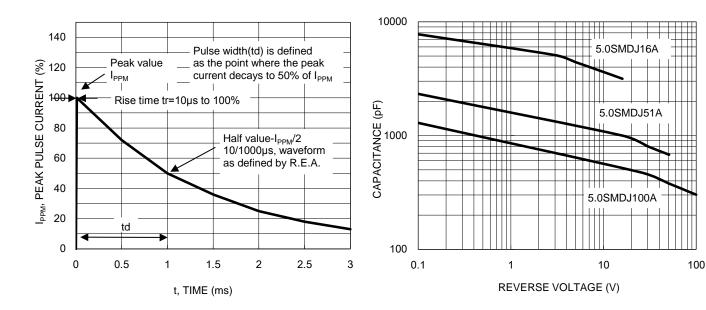


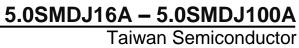
Fig.3 Pulse Waveform

6.5 6.0 5.5 5.0 4.5 4.0 3.5 3.0 2.5 2.0 1.5 Heat sink 1.0 16mm x 16mm 0.5 Cu pad test board 0.0 0 25 50 75 100 125 150 175 LEAD TEMPERATURE (°C)

Fig.2 Power Derating Curve

**Fig.4 Typical Junction Capacitance** 

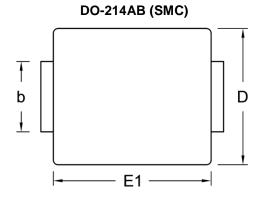


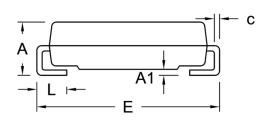


# **PACKAGE OUTLINE DIMENSIONS**

TAIWAN SEMICONDUCTOR

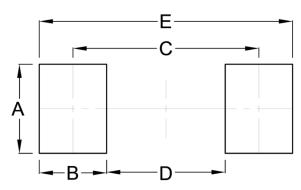
<del>Б</del>





DIM.	Unit (mm)		Unit (inch)	
	Min.	Max.	Min.	Max.
A	2.00	2.62	0.079	0.103
A1	0.10	0.20	0.004	0.008
b	2.90	3.20	0.114	0.126
с	0.15	0.31	0.006	0.012
D	5.59	6.22	0.220	0.245
E	7.75	8.13	0.305	0.320
E1	6.60	7.11	0.260	0.280
L	1.00	1.60	0.039	0.063

# SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	3.30	0.130
В	2.50	0.098
С	6.90	0.272
D	4.40	0.173
E	9.40	0.370

# **MARKING DIAGRAM**



- P/N = Marking Code
- G = Green Compound
- YW = Date Code
- F = Factory Code



# 5.0SMDJ16A - 5.0SMDJ100A

Taiwan Semiconductor

# Notice

Specifications of the products displayed herein are subject to change without notice. TSC or anyone on its behalf, assumes no responsibility or liability for any errors or inaccuracies.

Purchasers are solely responsible for the choice, selection, and use of TSC products and TSC assumes no liability for application assistance or the design of Purchasers' products.

Information contained herein is intended to provide a product description only. No license, express or implied, to any intellectual property rights is granted by this document. Except as provided in TSC's terms and conditions of sale for such products, TSC assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of TSC products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify TSC for any damages resulting from such improper use or sale.